

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CINDY FLENNIKEN	06/22/2017
CHUN D. LEE	06/22/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	EQUISTAR CHEMICALS, LP
<b>Street Address:</b>	1221 MCKINNEY STREET, SUITE 700
<b>Internal Address:</b>	LYONDELLBASELL TOWER
<b>City:</b>	HOUSTON
<b>State/Country:</b>	TEXAS
<b>Postal Code:</b>	77010
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15993118
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<b>ATTORNEY DOCKET NUMBER:</b>	HC7039
<b>NAME OF SUBMITTER:</b>	LESLIE STREETER
<b>SIGNATURE:</b>	/LESLIE STREETER/
<b>DATE SIGNED:</b>	11/02/2018
<b>Total Attachments: 2</b>	
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source=HC7039P1_ExecutedAssignment#page2.tif	

**ASSIGNMENT OF PROVISIONAL APPLICATION**

**WHEREAS:**

WHEREAS,

**Inventor**, Cindy Flenniken, 1221 McKinney Street, Suite 700, Houston, Texas 77010 and  
**Inventor**, Chun D. Lee, 1221 McKinney Street, Suite 700, Houston, Texas 77010

(hereinafter referred to as ASSIGNORS), have invented and own a certain invention entitled  
**METHODS OF CROSSLINKING AND COMPOSITIONS** for which a provisional patent  
application of the United States has been filed on May 31, 2017 under Serial No. 62/513,021,

WHEREAS, ASSIGNOR assigned to:

Equistar Chemicals, LP  
LyondellBasell Tower  
1221 McKinney Street, Suite 700  
Houston, Texas 77010  
United States of America

(hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire interest in, to and under  
said invention and in, to and under Letters Patent or similar legal protection to be obtained  
therefore in the United States and in any and all foreign countries.

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that in consideration  
of the payment by ASSIGNEE to ASSIGNORS of the sum of One Dollar (\$1.00), the receipt of  
which is hereby acknowledged, and for other good and valuable consideration, ASSIGNORS  
hereby sell, assign and transfer to ASSIGNEE the full and exclusive right, title and interest to said  
invention in the United States and its territorial possessions and in all foreign countries and to all  
Letters Patent or similar legal protection in the United States and its territorial possessions and in  
any and all foreign countries to be obtained for said invention by said application or any  
continuation, division, renewal, substitute or reissue thereof or any legal equivalent thereof in a  
foreign country for the full term or terms for which the same may be granted.

ASSIGNORS hereby covenant that no assignment, sale, agreement, or encumbrance has been or  
will be made or entered into which would conflict with this assignment and sale.

ASSIGNORS further covenant that ASSIGNEE will, upon its request, be provided promptly with  
all pertinent facts and documents relating to said application, said invention and said Letters  
Patent as may be known and accessible to ASSIGNORS and will testify as to the same in any  
interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or  
its legal representative any and all papers, instruments or affidavits required to apply for, obtain,  
maintain and enforce said application, said invention and said Letters Patent which may be  
necessary or desirable to carry out the purposes hereof.

ASSIGNORS grant ASSIGNEE permission to complete the filing date and Serial No. upon receipt of such information, including after signature by ASSIGNORS.

Signature of Inventors:

Cindy Flenniken  
Cindy Flenniken

June 23, 2017  
Date

Chun D. Lee  
Chun D. Lee

6/27/2017  
Date